



Material Content Data Sheet



Sales Product Name		BTS7010-2EPA		Issued		9. January 2019			
MA#		MA004199370							
Package		PG-TSDSO-14-22		Weight*		65.37 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	1.328	2.03	2.03	20312	20312	
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		144		
	non noble metal	zinc	7440-66-6	0.038	0.06		577		
	non noble metal	iron	7439-89-6	0.754	1.15		11534		
wire	non noble metal	copper	7440-50-8	30.617	46.84	48.06	468339	480594	
	non noble metal	copper	7440-50-8	0.921	1.41	1.41	14082	14082	
	encapsulation	organic material	carbon black	1333-86-4	0.086	0.13		1322	
plating	plastics	epoxy resin	-	3.371	5.16		51561		
	inorganic material	silicondioxide	60676-86-0	25.353	38.78	44.07	387810	440693	
	non noble metal	tin	7440-31-5	1.642	2.51	2.51	25112	25112	
glue	noble metal	silver	7440-22-4	0.816	1.25	1.25	12483	12483	
*deviation	< 10%	plastics	epoxy resin	-	0.077	0.12		1177	
		noble metal	silver	7440-22-4	0.363	0.55	0.67	5547	6724
Sum in total:						100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com